

## ABSTRACT OF THE DISCLOSURE

A polishing composition comprising 0.03 to 0.5% by weight of an organic acid or a salt thereof, an abrasive and water, wherein the abrasive has a surface potential of from -140 to 200 mV; a roll-off reducing agent comprising an inorganic compound having a property of controlling a surface potential of an abrasive in a polishing composition, wherein a surface potential of the abrasive in a standard polishing composition is controlled to -110 to 250 mV by the presence of the inorganic compound, wherein the standard polishing composition is prepared which comprises 20 parts by weight of an abrasive, the abrasive being high-purity alumina having  $\text{Al}_2\text{O}_3$  purity of 98.0% by weight or more composed of  $\alpha$ -type co-random crystal, 1 part by weight of citric acid, 78 parts by weight of water and 1 part by weight of an inorganic compound. The polishing composition or the roll-off reducing agent composition can be favorably used in polishing the substrate for precision parts.